Supply Chain Explorer: Substrates

This is an export from the Emerging Technology Observatory **Supply Chain Explorer** (https://chipexplorer.eto.tech). You can see the web version of this content at <a href="https://chipexplorer.eto.tech/?filter-choose=input-resource&input-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-resource=nput-

Substrates

Protective ceramic packages, plastic substrates, or encapsulant resins may be bonded to a chip during the packaging process.

Supplier countries

- China (mainland)
- Japan
- South Korea
- Taiwan

Notable supplier companies

- · AKM China (mainland)
- Ibiden Japan
- NanYa Taiwan
- · Samsung South Korea
- Shennan Circuits China (mainland)
- Shinko Japan
- Zhuhai Yueya China (mainland)